

67,200-635; TSMC 01-0141  
Serial Number 10/047,162

### LISTING OF THE CLAIMS

The following Listing of the Claims replaces all previous listings of the claims within this application.

No claims are amended or added herein.

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- 1 1. (original) A microelectronic fabrication facility information system comprising:  
2 a series of databases having contained therein production information for microelectronic  
3 fabrication product orders within a microelectronic fabrication facility; and  
4 a microelectronic fabrication facility communication interface connected to the series of  
5 databases, where the microelectronic fabrication facility communication interface serves as an  
6 interface to a distributed communication network and functions in a fashion which allows a  
7 microelectronic fabrication customer also connected to the distributed communications network  
8 to access the information within the series of databases.

- 1 2. (original) The system of claim 1 wherein the system is incorporated into a microelectronic  
2 fabrication facility selected from the group consisting of integrated circuit microelectronic  
3 fabrication facilities, ceramic substrate microelectronic fabrication facilities, solar cell  
4 optoelectronic microelectronic fabrication facilities, sensor image array optoelectronic  
5 microelectronic facilities and display image array optoelectronic microelectronic fabrication  
6 facilities.

- 1 3. (original) The system of claim 1 wherein the microelectronic fabrication facility  
2 communication interface is a computer server.

- 1 4. (original) The system of claim 3 wherein the computer server has incorporated therein the  
2 series of databases.

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1 5. (original) The system of claim 1 wherein the distributed communications network is selected  
2 from the group consisting of local area networks, wide area networks, Internet networks and  
3 intranet networks.

1 6. (original) The system of claim 1 wherein the distributed communications network is an  
2 Internet distributed communications network.

1 7. (original) A method for operating a microelectronic fabrication facility information system  
2 comprising:

3 providing a microelectronic fabrication facility information system comprising:

4 a series of databases having contained therein production information for  
5 microelectronic fabrication product orders within a microelectronic fabrication facility; and

6 a microelectronic fabrication facility communication interface connected to the  
7 series of databases, where the microelectronic fabrication facility communication interface  
8 serves as an interface to a distributed communication network and functions in a fashion which  
9 allows a microelectronic fabrication customer also connected to the distributed communications  
10 network to access the information within the series of databases;

11 providing the microelectronic fabrication customer connected to the distributed  
12 communications network; and

13 effecting access of the production information within the series of databases by the  
14 microelectronic fabrication customer through the distributed communications network.

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1 8. (original) The method of claim 7 wherein the system is incorporated into a microelectronic  
2 fabrication facility selected from the group consisting of integrated circuit microelectronic  
3 fabrication facilities, ceramic substrate microelectronic fabrication facilities, solar cell  
4 optoelectronic microelectronic fabrication facilities, sensor image array optoelectronic  
5 microelectronic facilities and display image array optoelectronic microelectronic fabrication  
6 facilities.

1 9. (original) The method of claim 7 wherein the microelectronic fabrication facility  
2 communication interface is a computer server.

1 10. (original) The method of claim 9 wherein the computer server has incorporated therein the  
2 series of databases.

1 11. (original) The method of claim 7 wherein the distributed communications network is  
2 selected from the group consisting of local area networks, wide area networks, Internet networks  
3 and intranet networks.

1 12. (original) The method of claim 7 wherein the distributed communications network is an  
2 Internet distributed communications network.

1 13. (previously presented) The microelectronic fabrication information system of claim 1  
2 wherein the microelectronic fabrication information system allows for a customer to access to  
3 the customer's product order information within the microelectronic fabrication facility.

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- 1 14. (previously presented) The method of claim 7 wherein the microelectronic fabrication
- 2 information system allows for a customer to access to the customer's product order within the
- 3 microelectronic fabrication facility.